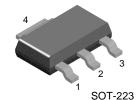


NZT749

PNP Current Driver Transistor

- This device is designed for power amplifier, regulator and switching circuit where speed is important.
- Sourced from process 5P.



1. Base 2, 4. Collector 3. Emitter

Rev. A, July 2004

Absolute Maximum Ratings* T_a=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CEO}	Collector-Emitter Voltage	-25	V
V _{CBO}	Collector-Base Voltage	-35	V
V _{EBO}	Emitter-Base Voltage	-5.0	V
I _C	Collector Current (DC) - Continuous	-4.0	Α
T _J , T _{STG}	Operating and Storage Junction Temperature Range	- 55 ~ 150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

Electrical Characteristics T_a=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units		
Off Characteristics							
V _{(BR)CEO}	Collector-Emitter Voltage	$I_{C} = -10 \text{mA}, I_{B} = 0$	-25		V		
V _{(BR)CBO}	Collector-Base Voltage	$I_C = -100\mu A, I_E = 0$	-35		V		
V _{(BR)EBO}	Emitter-Base Voltage	$I_E = -10\mu A, I_C = 0$	-5.0		V		
I _{CBO}	Collector Cut-off Current	$V_{CB} = -30V, I_{E} = 0$		-100	nA		
I _{EBO}	Emitter Cut-off Current	$V_{EB} = -4V, I_{C} = 0$		-0.1	μΑ		
On Characte	eristics *	•	•	•	•		
h _{FE}	DC Current Gain	$V_{CE} = -2.0V, I_{C} = -50 \text{mA}$ $V_{CE} = -2.0V, I_{C} = -1.0 \text{A}$ $V_{CE} = -2.0V, I_{C} = -2.0 \text{A}$	70 80 65	300			
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C = -1.0A, I _B = -100mA		-0.3	V		
V _{BE(sat)}	Base-Emitter Saturation Voltage	I _C = -1.0A, I _B = -100mA		-1.25	V		
V _{BE(on)}	Base-Emitter On Voltage	$I_C = -1.0A, V_{CE} = -2.0V$		-1.0	V		
Small Signa	I Characteristics	•	•	•	•		
f _T	Current gain Bandwidth Product	$V_{CE} = -5.0V, I_{C} = -50mA$ f = 100MHz	75		MHz		

^{*} Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

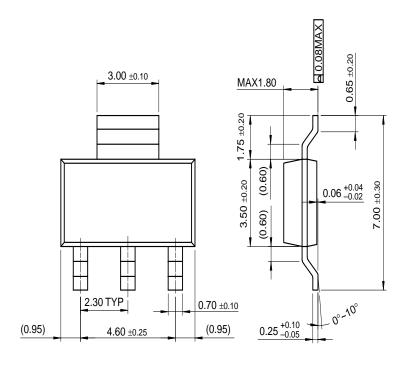
Thermal Characteristics T_a=25°C unless otherwise noted

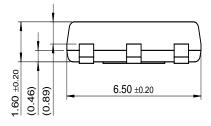
Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation	1.2	W
	Derate above 25°C	9.7	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	103	°C/W

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Package Dimensions

SOT-223





Dimensions in Millimeters

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